

## 110-93-632-41-801000

#### 110-93-632-41-801000 Information

Heisener.com	 110-93-632-41-801000 Mill-Max Manufacturing Corp. Connectors, Interconnects Sockets for ICs, Transistors CONN IC DIP SOCKET 32POS GOLD - For the pricing/inventory/lead time, please contact	
For Reference Only	us Website: https://www.heisener.com E-mail: salesdept@heisener.com	Request a Quote

## **Certified Quality**

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.



## 110-93-632-41-801000 Specifications

Manufacturer Mill-Max Manufacturing Corp.   Category Connectors, Interconnects   Sockets for ICs, Transistors Sockets for ICs, Transistors   Package -   Series 110   Type DIP, 0.6" (15.24mm) Row Spacing   Number of Positions or Pins (Grid) 32 (2 x 16)   Pitch - Mating 0.100" (2.54mm)   Contact Finish - Mating Gold   Contact Finish - Mating 30µin (0.76µm)   Contact Finish Thickness - Mating Beryllium Copper   Mounting Type Through Hole   Features Open Frame, Decoupling Capacitor   Pitch - Post 0.100" (2.54mm)   Contact Finish Thickness - Post 0.100" (2.54mm)   Contact Material - Mating Beryllium Copper   Predures Open Frame, Decoupling Capacitor   Termination Solder   Contact Finish - Post 0.100" (2.54mm)   Contact Finish Thickness - Post 200µin (5.08µm)   Contact Finish Thickness - Post 200µin (5.08µm)   Contact Material - Post Brass Alloy   Contact Material - Post Brass			
CategoryConnectors, Interconnects Sockets for ICs, TransistorsPackage-Series110TypeDIP, 0.6" (15.24mm) Row SpacingNumber of Positions or Pins (Grid)32 (2 x 16)Ottor (2.54mm)0.100" (2.54mm)Contact Finish - MatingGoldContact Finish Thickness - Mating30µin (0.76µm)Contact Finish Thickness - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorPerintinationSolderContact Finish Post0.100" (2.54mm)Contact Finish PostDino" (2.54mm)Contact Finish PostSolderContact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyContact Material PostBrass AlloyContact Material PostSras AlloyContact Mater	Manufacturer Part Number	110-93-632-41-801000	
Sockets for ICs, TransistorsPackage-Series110TypeDIP, 0.6" (15.24mm) Row SpacingNumber of Positions or Pins (Grid)32 (2 x 16)Pitch - Mating0.100" (2.54mm)Contact Finish - MatingGoldContact Finish Thickness - Mating30µin (0.76µm)Contact Finish Thickness - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish Thickness - Post200µin (5.08µm)Contact Finish Thickness - Post200µin (5.08µm)Contact Finish Thickness - PostPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Manufacturer	Mill-Max Manufacturing Corp.	
Package-Series110TypeDIP, 0.6" (15.24mm) Row SpacingNumber of Positions or Pins (Grid)32 (2 x 16)Pitch - Mating0.100" (2.54mm)Contact Finish - MatingGoldContact Finish Thickness - Mating30µin (0.76µm)Contact Material - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish Thickness - Post200µin (5.08µm)Contact Finish Thickness - Post200µin (5.08µm)Contact Finish Thickness - PostBrass AlloyContact Material - PostPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Category	Connectors, Interconnects	
Number110TypeDIP, 0.6" (15.24mm) Row SpacingNumber of Positions or Pins (Grid)32 (2 x 16)Pitch - Mating0.100" (2.54mm)Contact Finish - MatingGoldContact Finish - Mating30µin (0.76µm)Contact Material - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorPitch - Post0.100" (2.54mm)Contact Finish - Post0.100" (2.54mm)Contact Finish - Post0.100" (2.54mm)Contact Finish - Post0.100" (2.54mm)Contact Finish Thickness - Post200µin (5.08µm)Contact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C		Sockets for ICs, Transistors	
TypeDIP, 0.6" (15.24mm) Row SpacingNumber of Positions or Pins (Grid)32 (2 x 16)Pitch - Mating0.100" (2.54mm)Contact Finish - MatingGoldContact Finish Thickness - Mating30µin (0.76µm)Contact Material - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish Thickness - Post0.100" (2.54mm)Contact Finish Thickness - Post0.100" (2.54mm)Contact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Package	-	
Number of Positions or Pins (Grid)32 (2 x 16)Pitch - Mating0.100" (2.54mm)Contact Finish - MatingGoldContact Finish Thickness - Mating30µin (0.76µm)Contact Material - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish Thickness - Post200µin (5.08µm)Contact Material - PostEass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Series	110	
Pitch - Mating0.100" (2.54mm)Contact Finish - MatingGoldContact Finish Thickness - Mating30µin (0.76µm)Contact Material - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - Post0.100" (2.54mm)Contact Finish - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Туре	DIP, 0.6" (15.24mm) Row Spacing	
Contact Finish - MatingGoldContact Finish Thickness - Mating30µin (0.76µm)Contact Material - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - Post20µin (5.08µm)Contact Finish Thickness - PostBrass AlloyHousing Material - PostPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterHousing MaterialSo°C ~ 125°C	Number of Positions or Pins (Grid)	32 (2 x 16)	
Contact Finish Thickness - Mating30µin (0.76µm)Contact Material - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorFeaturesSolderPitch - Post0.100" (2.54mm)Contact Finish - PostTin-LeadContact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Pitch - Mating	0.100" (2.54mm)	
Contact Material - MatingBeryllium CopperMounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - PostTin-LeadContact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Contact Finish - Mating	Gold	
Mounting TypeThrough HoleFeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - PostTin-LeadContact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Contact Finish Thickness - Mating	30µin (0.76µm)	
FeaturesOpen Frame, Decoupling CapacitorTerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - PostTin-LeadContact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Contact Material - Mating	Beryllium Copper	
TerminationSolderPitch - Post0.100" (2.54mm)Contact Finish - PostTin-LeadContact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Mounting Type	Through Hole	
Pitch - Post0.100" (2.54mm)Contact Finish - PostTin-LeadContact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Features	Open Frame, Decoupling Capacitor	
Contact Finish - PostTin-LeadContact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Termination	Solder	
Contact Finish Thickness - Post200µin (5.08µm)Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Pitch - Post	0.100" (2.54mm)	
Contact Material - PostBrass AlloyHousing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Contact Finish - Post	Tin-Lead	
Housing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Contact Finish Thickness - Post	200µin (5.08µm)	
Operating Temperature $-55^{\circ}C \sim 125^{\circ}C$	Contact Material - Post	Brass Alloy	
	Housing Material	Polycyclohexylenedimethylene Terephthalate (PCT), Polyester	
Report errors?	Operating Temperature	-55°C ~ 125°C	
			Report errors?

#### 110-93-632-41-801000 Guarantees



**Quality Guarantees** 

We provide 90 days warranty. \* If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.

# SERVICE BUARANTEE

#### **Service Guarantees**

We guarantee 100% customer satisfaction. Our experienced sales team and tech support team back our services to satisfy all our customers.

### 110-93-632-41-801000 Payment Methods





If you have any question about 110-93-632-41-801000, please do not hesitate to contact us! Website: https://www.heisener.com E-mail: salesdept@heisener.com